

Title (en)
PLATE FOR A PLASMA PANEL WITH REINFORCED POROUS BARRIERS

Title (de)
PLATTE FÜR PLASMASCHIRM MIT VERSTÄRKTEN PORÖSEN BARRIEREN

Title (fr)
DALLE POUR PANNEAU A PLASMA A BARRIERES POREUSES RENFORCEES

Publication
EP 1415316 A2 20040506 (FR)

Application
EP 02745478 A 20020604

Priority
• FR 0201868 W 20020604
• FR 0108628 A 20010629
• FR 0112250 A 20010921

Abstract (en)
[origin: WO03003398A2] A plate comprising a substrate (10) covered with at least one network of electrodes (11), said network being covered with a network of barriers (17) made of a mineral material with a porosity of more than 25 %, comprising a porous-based underlayer (18) which is placed inbetween the network of electrodes (11) and the network of barriers (17), and which is made of a mineral material with a porosity of more than 25 %. Reinforced porous barriers are obtained. Advantageously, the plate does not comprise a specific dielectric layer; the number of manufacturing steps is limited and the plate can be produced entirely at low temperature.

IPC 1-7
H01J 7/04; **H01J 17/16**; **H01J 17/49**; **H01J 9/02**; **H01J 9/24**

IPC 8 full level
H01J 9/02 (2006.01); **H01J 9/24** (2006.01); **H01J 11/02** (2006.01); **H01J 11/12** (2012.01); **H01J 11/34** (2012.01); **H01J 11/36** (2012.01); **H01J 11/44** (2012.01); **H01J 17/04** (2006.01); **H01J 17/16** (2006.01); **H01J 17/49** (2006.01)

CPC (source: EP KR US)
H01J 9/242 (2013.01 - EP US); **H01J 11/12** (2013.01 - EP US); **H01J 11/34** (2013.01 - KR); **H01J 11/36** (2013.01 - EP KR US); **H01J 11/44** (2013.01 - KR); **H01J 2211/361** (2013.01 - EP US); **H01J 2211/366** (2013.01 - EP US)

Citation (search report)
See references of WO 03003398A2

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
WO 03003398 A2 20030109; **WO 03003398 A3 20031106**; AU 2002317214 A1 20030303; CN 100505137 C 20090624; CN 1526152 A 20040901; DE 60230875 D1 20090305; EP 1415316 A2 20040506; EP 1415316 B1 20090114; JP 2004531041 A 20041007; JP 4324466 B2 20090902; KR 100852678 B1 20080819; KR 20040012968 A 20040211; TW I294136 B 20080301; US 2004169471 A1 20040902; US 7339318 B2 20080304

DOCDB simple family (application)
FR 0201868 W 20020604; AU 2002317214 A 20020604; CN 02812092 A 20020604; DE 60230875 T 20020604; EP 02745478 A 20020604; JP 2003509482 A 20020604; KR 20037016863 A 20031224; TW 91114255 A 20020628; US 48136003 A 20031218